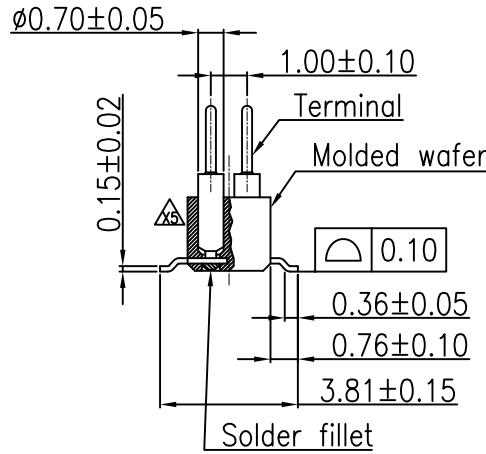
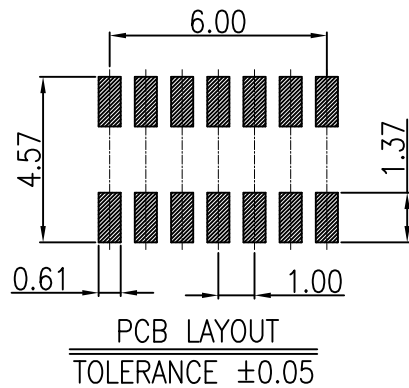
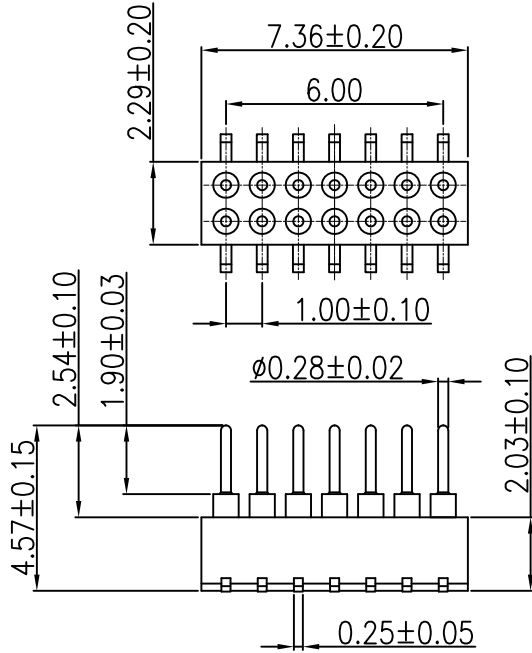
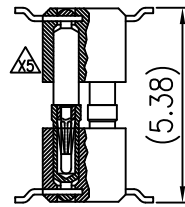


REVISIONS				
SYM	ECN No.	DESCRIPTION	DATE	APPROVED
A		MASS-PRODUCTION	03/13/2020	James



▲The plating ball should be full



NOTES:

MATERIAL:

1. HOUSING: LCP,UL 94V-0. COLOR:BLACK
2. PIN(CONTACT): COPPER ALLOY.

PLATED:

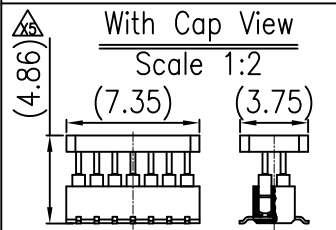
1. CONTACT AREA : PLATING GOLD 0.38 MICROMETERS MIN OVER 1.27~2.54 MICROMETERS NICKEL.
2. SOLDER NAIL: PLATING MATTE TIN 2.54~5.08 MICROMETERS OVER 1.27~2.54 MICROMETERS NICKEL.

ELECTRICAL

1. CURRENT RATING:1A.
2. VOLTAGE RATING:250V DC/AC.
3. CONTACT RESISTANCE:20 mΩ MAX.
4. INSULATION RESISTANCE:5000MΩ MIN.
5. DIELECTRIC VOLTAGE:500V AC/1MINUTE.
6. TEMPERATURE RISE:30°C MAX

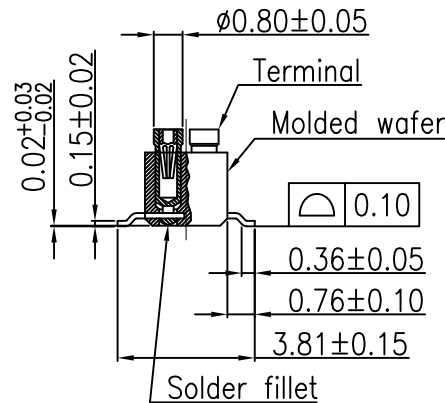
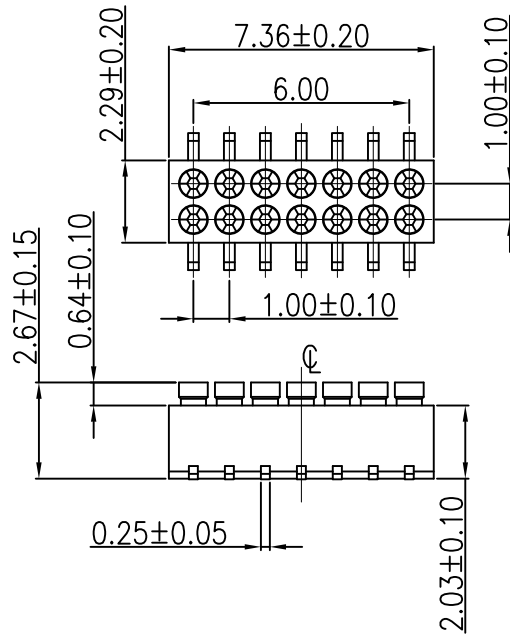
ENVIRONMENTAL:

1. OPERATION TEMPERATURE:-40°C~+105°C.
2. REFLOW SOLDERING:260°C±5°C,30S.
3. ENVIRONMENTAL REQUIREMENT:ACCORDING TO RoHS STANDARD.

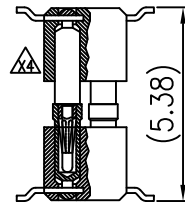
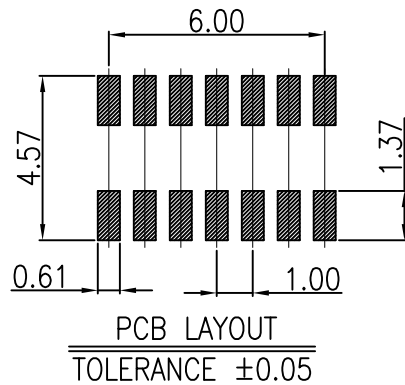


TOLERANCE UNIT(mm)	APPROVALS	DATE	CSG Industrial Co.,Ltd http://www.csg-china.com			
x. ±0.30	DRAWN Nio	03/13/2020	TITLE 1.0 PITCH SMT Vertical Angle Wafer 14PIN H2.03			
x.x ±0.25	CHECKED James	03/13/2020	SCALE N.A.	PART NO. B1000VS207LPG2B0001	DRAWING NO. B1000VS207LPG2B0001 A	REV. A
x.xx ±0.15	APPROVED James	03/13/2020	SHEET 1 OF 1	CUSTOMER CODE	CUSTOMER PART NO.	
x.xxx ±0.10			UNIT MM			
ANGULAR ±2°						
UNLESS OTHERWISE SPECIFIED						

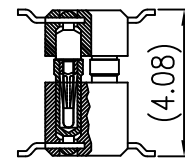
REVISIONS				
SYM	ECN No.	DESCRIPTION	DATE	APPROVED
A		MASS-PRODUCTION	03/13/2020	James



▲ The planting ball should be full



Matting Height



Matting Height

NOTES:

MATERIAL:

1. HOUSING: LCP,UL 94V-0. COLOR:BLACK
2. PIN(CONTACT): COPPER ALLOY.

PLATED:

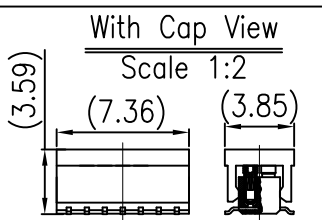
1. CONTACT: PLATING GOLD 0.0254 MICROMETERS MIN OVER 1.27~2.54MICROMETERS NICKEL. (EXCEPT CONTACT AREA).
2. CONTACT AREA : PLATING GOLD 0.38 MICROMETERS MIN OVER 1.27~2.54MICROMETERS NICKEL.
3. SOLDER NAIL: PLATING MATTE TIN 2.54~5.08 MICROMETERS OVER 1.27~2.54MICROMETERS NICKEL.

ELECTRICAL

1. CURRENT RATING:1A.
2. VOLTAGE RATING:250V DC/AC.
3. CONTACT RESISTANCE:20 mΩ MAX.
4. INSULATION RESISTANCE:5000MΩ MIN.
5. DIELECTRIC VOLTAGE:500V AC/1MINUTE.
6. TEMPERATURE RISE:30°C MAX

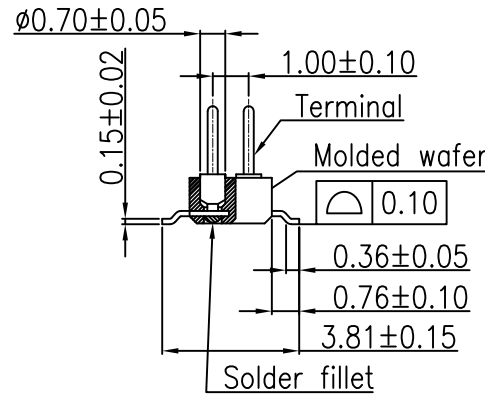
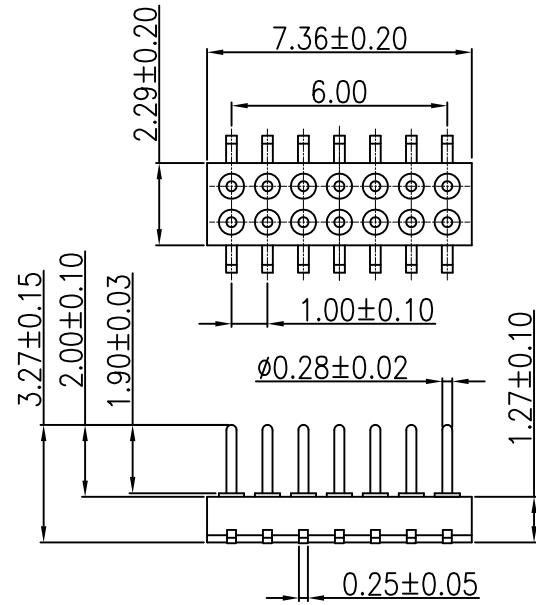
ENVIRONMENTAL:

1. OPERATION TEMPERATURE:-40°C~+105°C.
2. REFLOW SOLDERING:260°C±5°C,30S.
3. ENVIRONMENTAL REQUIREMENT:ACCORDING TO RoHS STANDARD.

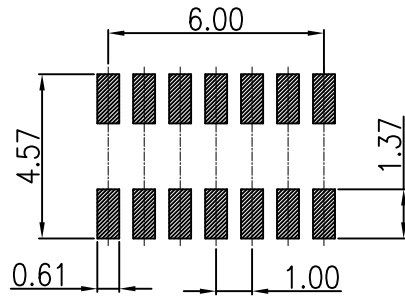


TOLERANCE UNIT(mm)	APPROVALS	DATE	CSG Industrial Co.,Ltd http://www.csg-china.com			
X. ±0.30	DRAWN Nio	03/13/2020	TITLE 1.0 PITCH SMT Vertical Angle Wafer 14PIN H2.03			
X.X ±0.25	CHECKED James	03/13/2020				
X.XX ±0.15	APPROVED James	03/13/2020				
X.XXX ±0.10			SCALE N.A.	PART NO.	DRAWING NO.	REV.
ANGULAR ±2'			SHEET 1 OF 1	B1000VS207LPG2B0002	B1000VS207LPG2B0002 A	A
UNLESS OTHERWISE SPECIFIED		UNIT MM	CUSTOMER CODE	CUSTOMER PART NO.	DHS214-844-GG-M	

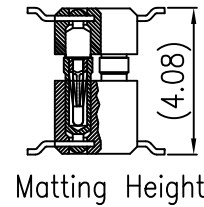
REVISIONS				
SYM	ECN No.	DESCRIPTION	DATE	APPROVED
A		MASS-PRODUCTION	05/13/2022	James



▲The planting ball should be full



PCB LAYOUT
TOLERANCE ±0.05



NOTES:
MATERIAL:

- HOUSING: LCP,UL 94V-0. COLOR:BLACK
- PIN(CONTACT): COPPER ALLOY.

PLATED:

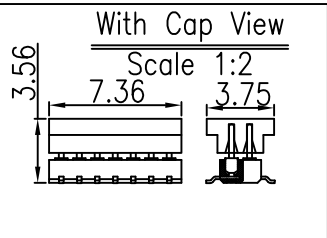
- CONTACT AREA : PLATING GOLD 0.38 MICROMETERS MIN OVER 1.27~2.54 MICROMETERS NICKEL.
- SOLDER NAIL: PLATING MATTE TIN 2.54~5.08 MICROMETERS OVER 1.27~2.54 MICROMETERS NICKEL.

ELECTRICAL

- CURRENT RATING:1A.
- VOLTAGE RATING:250V DC/AC.
- CONTACT RESISTANCE:20 mΩ MAX.
- INSULATION RESISTANCE:5000MΩ MIN.
- DIELECTRIC VOLTAGE:500V AC/1MINUTE.
- TEMPERATURE RISE:30°C MAX

ENVIRONMENTAL:

- OPERATION TEMPERATURE:-40°C~+105°C.
- REFLOW SOLDERING:260°C±5°C,30S.
- ENVIRONMENTAL REQUIREMENT:ACCORDING TO RoHS STANDARD.



TOLERANCE UNIT(mm)	APPROVALS	DATE	CSG Industrial Co.,Ltd http://www.csg-china.com			
X. ±0.30	DRAWN Nio	05/13/2022	TITLE 1.0 PITCH SMT Vertical Angle Wafer 14PIN H1.27			
X.X ±0.25	CHECKED James	05/13/2022				
X.XX ±0.15	APPROVED James	05/13/2022				
X.XXX ±0.10			SCALE N.A.	PART NO.	DRAWING NO.	REV.
ANGULAR ±2'			SHEET 1 OF 1	B1000VS207LPG2B0003	B1000VS207LPG2B0003 A	A
UNLESS OTHERWISE SPECIFIED		UNIT MM	CUSTOMER CODE	CUSTOMER PART NO.	DHAM-2-14-846-GH-M	